



- 6XSHU /RZ *DWH &KDUJH
- *UHHQ 'HYLFH \$YDLODEOH
- ([FHOOHQW &G9 GW HIIHFW GHFOLQH
- \$GYDQFHG KLJK FHOO GHQVLW\ %9'66

3URGXFW 6XPPD	5'621	,
9	P	\$

'HVFULSWLRQ

TO252 Pin Configuration

7KXW80P02 L W KHL JKH G D Q W L U H Q F K H G
 3 F 0 2 6) (7 V Z K L S K U R Y H G H O O H Q W
 5 ' 6 2 1 D Q G D W F K D U I R H R V R W K H
 V \ Q F K U R E Q F R Q Y H U S I O U F D W L R Q V
 7 K X W 8 0 P 0 2 P H H W S H R + D Q G U H H Q
 3 U R G X H W X L U Z I P W K D W Q F W H R Q D E L O L W \
 D S S U R Y H G

\$EVROXWH 0D[LPXP 5DWLQJV 7\$ f & XQOHVV RWKHUZLVH

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current	I _D	T _C =25°C	-
		T _C =100°C	-44
Pulsed Drain Current ¹	I _{DM}	-280	A
Single Pulse Avalanche Energy ²	EAS	80	mJ
Total Power Dissipation	P _D	43.1	W
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	R - _s	65	°C/W
Thermal Resistance from Junction-to-Case	R - _c	2.9	°C/W

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-20	-	-	V
Gate-body Leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±12V	-	-	±100	nA
Zero Gate Voltage Drain Current	T _J =25°C	V _{DS} = -20V, V _{GS} = 0V	-	-	-1	μA
	T _J =100°C		-	-	-100	
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-0.4	-0.7	-1	V
Drain-Source On-Resistance ⁴	R _{DS(on)}	V _{GS} = -4.5V, I _D = -10A	-	3.8	5.2	mΩ
		V _{GS} = -2.5V, I _D = -10A	-	5	6.8	
Forward Transconductance ⁴	g _{fs}	V _{DS} = -4.5V, I _D = -10A	-	56	-	S
Dynamic Characteristics⁵						
Input Capacitance	C _{iss}	V _{DS} = -10V, V _{GS} = 0V, f = 1MHz	-	4770	-	pF
Output Capacitance	C _{oss}		-	665	-	
Reverse Transfer Capacitance	C _{rss}		-	570	-	
Gate Resistance	R _g	f = 1MHz	-	9.6	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q _g	V _{GS} = -4.5V, V _{DS} = -10V, I _D = -10A	-	55	-	nC
Gate-Source Charge	Q _{gs}		-	5.2	-	
Gate-Drain Charge	Q _{gd}		-	10	-	
Turn-On Delay Time	t _{d(on)}	V _{GS} = -4.5V, V _{DD} = -10V, R _G = 3Ω, I _D = -10A	-	22	-	ns
Rise Time	t _r		-	38	-	
Turn-Off Delay Time	t _{d(off)}		-	110	-	
Fall Time	t _f		-	62	-	
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	I _S = -10A, V _{GS} = 0V	-	-	-1.2	V
Continuous Source Current	T _C =25°C	I _S	-	-	-	A

Note :

Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.

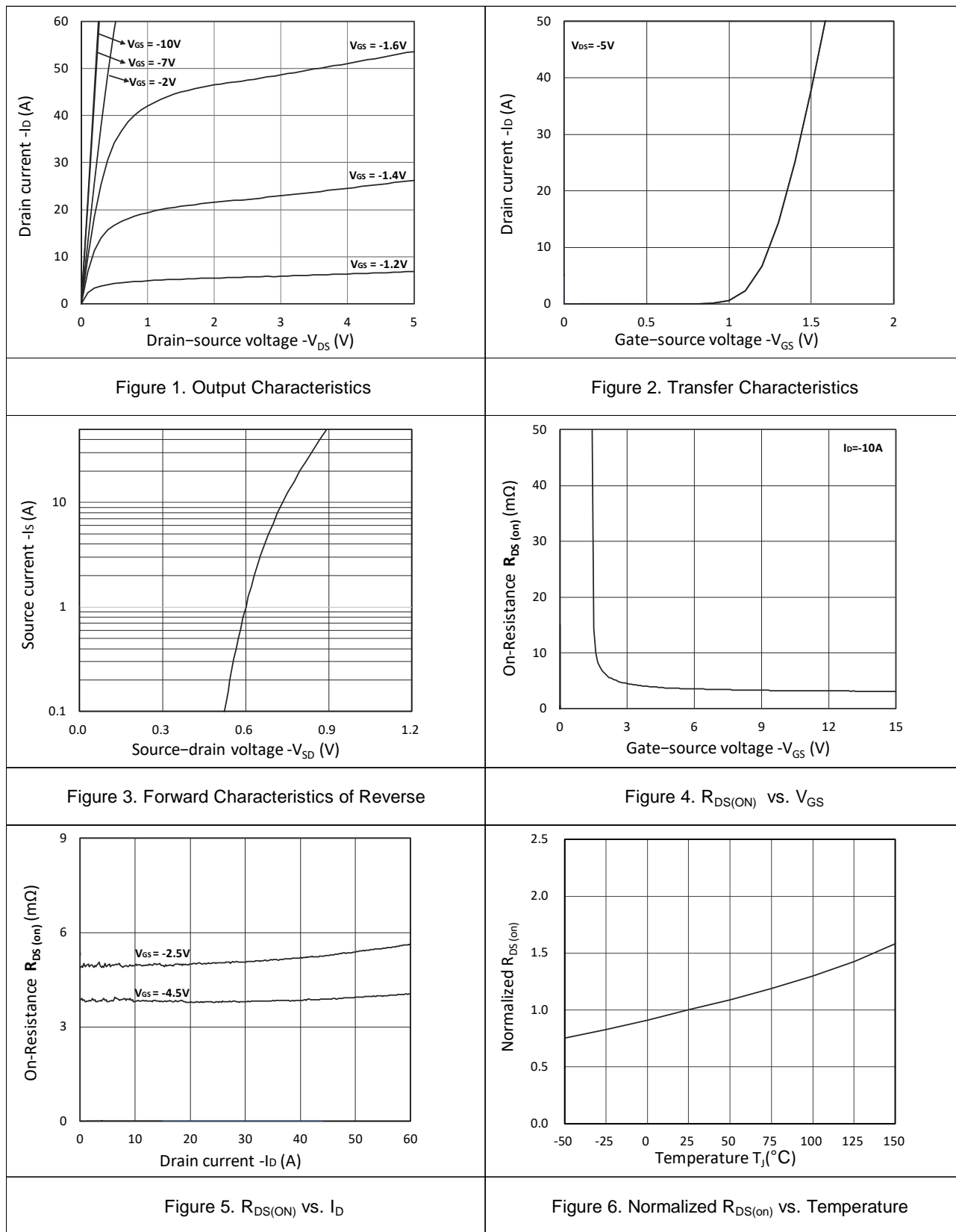
The EAS data shows Max. rating. The test condition is V_{DD}= -25V, V_{GS}= -10V, L= 0.4mH, I_{AS}= -20A.

The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.

The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.

This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics



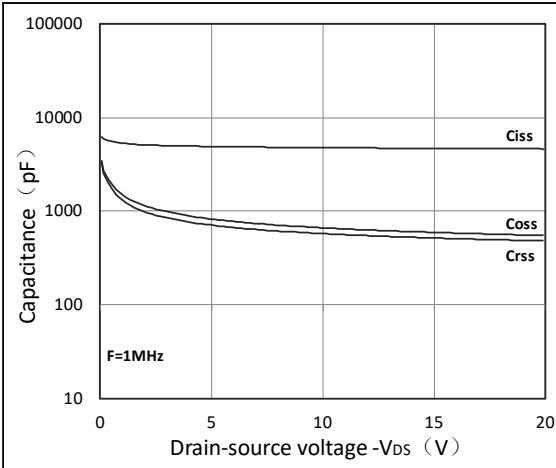


Figure 7. Capacitance Characteristics

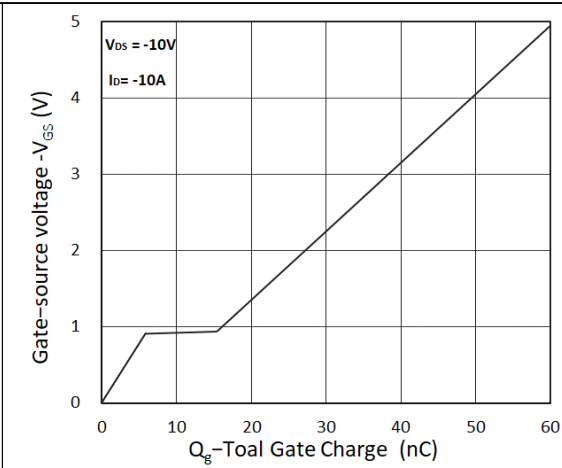


Figure 8. Gate Charge Characteristics

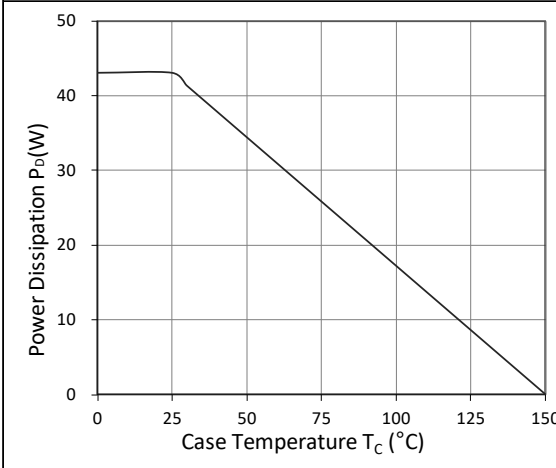


Figure 9. Power Dissipation

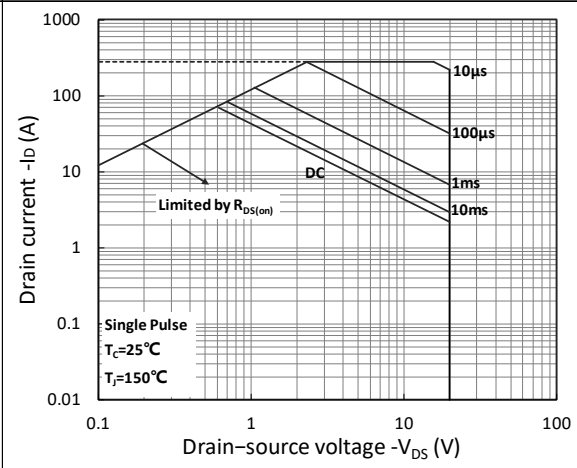


Figure 10. Safe Operating Area

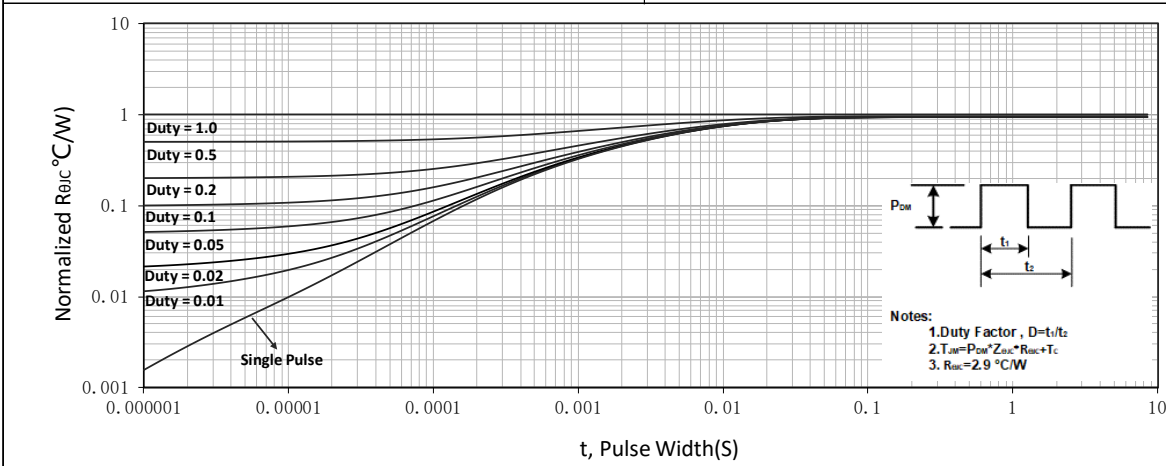
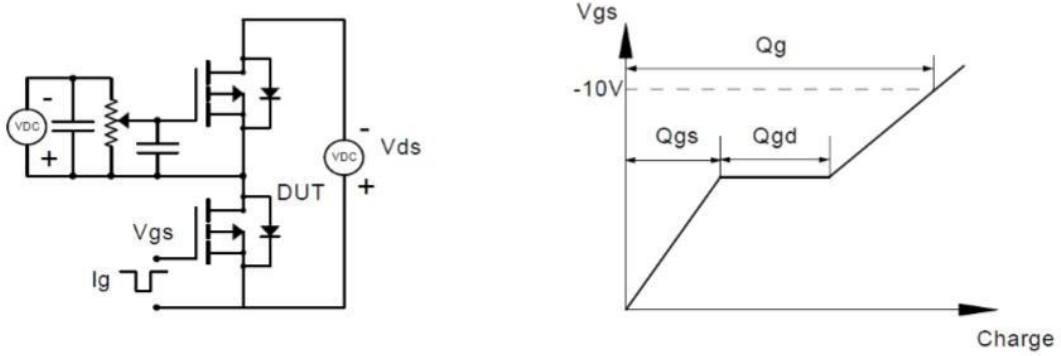


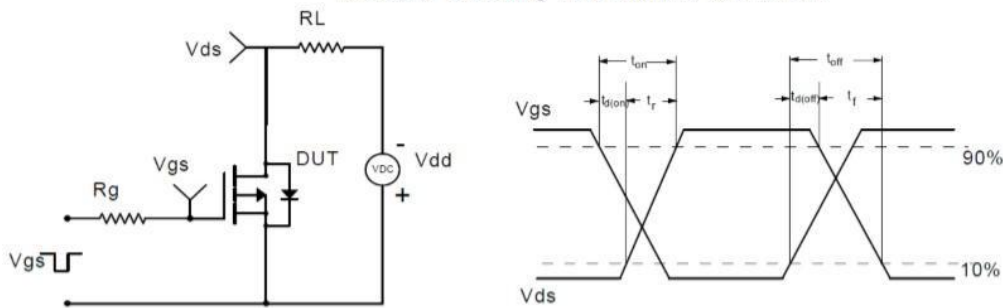
Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

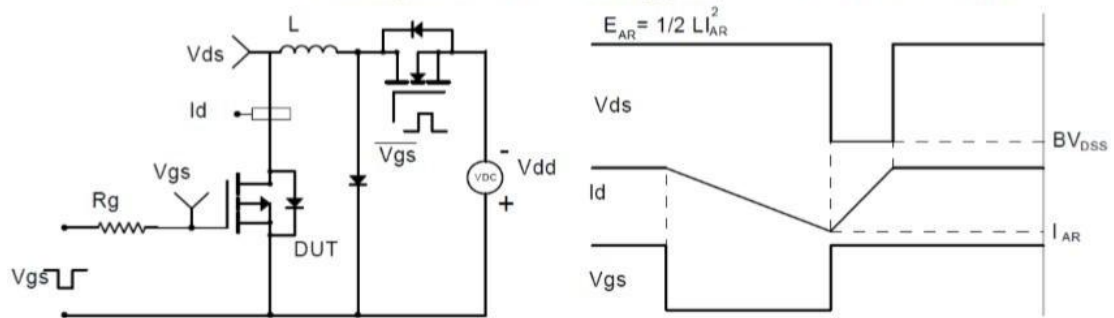
Gate Charge Test Circuit & Waveform



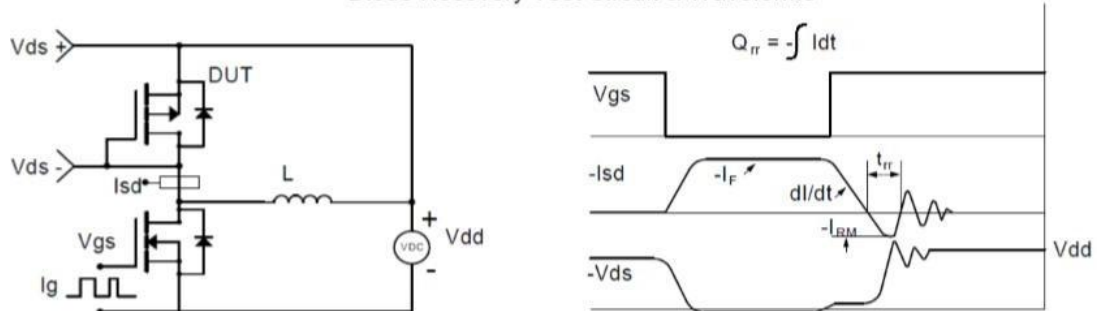
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Mechanical Data-TO-252

